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FDD86369

N-Channel PowerTrench[®] MOSFET 80 V, 90 A, 7.9 m Ω

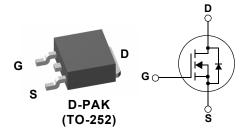
Features

- Typical R_{DS(on)} = 5.9 mΩ at V_{GS} = 10V, I_D = 80 A
- Typical $Q_{q(tot)}$ = 34 nC at V_{GS} = 10V, I_D = 80 A
- UIS Capability
- RoHS Compliant

Applications

- PowerTrain Management
- Solenoid and Motor Drivers
- Integrated Starter/Alternator
- Primary Switch for 12V Systems





For current package drawing, please refer to the ON website at http://www.fairchildsemi.com/package-drawings/TO/TO252A03.pdf

MOSFET Maximum Ratings T_J = 25°C unless otherwise noted.

Symbol	Parameter		Ratings	Units
V_{DSS}	Drain-to-Source Voltage		80	V
V_{GS}	Gate-to-Source Voltage		±20	V
	Drain Current - Continuous (V _{GS} =10) (Note 1)	T _C = 25°C	90	Α
'D	Pulsed Drain Current	T _C = 25°C	See Figure 4	_ A
E _{AS}	Single Pulse Avalanche Energy	(Note 2)	29	mJ
D	Power Dissipation		150	W
P_{D}	Derate Above 25°C		1.0	W/°C
T _J , T _{STG}	Operating and Storage Temperature		-55 to + 175	°C
$R_{\theta JC}$	Thermal Resistance, Junction to Case		1.0	°C/W
$R_{\theta JA}$	Maximum Thermal Resistance, Junction to Ambient	(Note 3)	52	°C/W

Notes

- 1: Current is limited by bondwire configuration.
- 2: Starting T_J = 25°C, L = 14 μ H, I_{AS} = 64A, V_{DD} = 80V during inductor charging and V_{DD} = 0V during time in avalanche.
- 3: R_{0,JA} is the sum of the junction-to-case and case-to-ambient thermal resistance, where the case thermal reference is defined as the solder mounting surface of the drain pins. R_{0,JC} is guaranteed by design, while R_{0,JA} is determined by the board design. The maximum rating presented here is based on mounting on a 1 in² pad of 2oz copper.

Package Marking and Ordering Information

Device Marking	Device	Package	Reel Size	Tape Width	Quantity
FDD86369	FDD86369	D-PAK(TO-252)	13"	16 mm	2500 units

Electrical Characteristics $T_J = 25$ °C unless otherwise noted.

Symbol	Parameter	Test Conditions		Min.	Тур.	Max.	Units	
Off Characteristics								
B _{VDSS}	Drain-to-Source Breakdown Voltage	I _D = 250μA, V _{GS}	_S = 0V	80	-	-	V	
I _{DSS}	Drain-to-Source Leakage Current	V _{DS} =80V, T _J	= 25°C	-	-	1	μА	
		$V_{GS} = 0V$ T_J	= 175°C (Note 4)	-	-	1	mA	
I _{GSS}	Gate-to-Source Leakage Current	$V_{GS} = \pm 20V$		1	-	±100	nA	

On Characteristics

$V_{GS(th)}$	Gate to Source Threshold Voltage	$V_{GS} = V_{DS}, I_{D} = 250 \mu A$		2.0	2.7	4.0	V
В	IDrain to Source On Resistance	I _D = 80A,	$T_{\rm J} = 25^{\rm o}{\rm C}$		5.9	7.9	mΩ
R _{DS(on)}		V _{GS} = 10V	$T_J = 175^{\circ}C \text{ (Note 4)}$		13.0	17.4	mΩ

Dynamic Characteristics

C _{iss}	Input Capacitance	101/11/	$V_{DS} = 40V, V_{GS} = 0V,$ f = 1MHz		2530	-	pF
C _{oss}	Output Capacitance				430	-	pF
C _{rss}	Reverse Transfer Capacitance	1 - 1101112			16	-	pF
R_g	Gate Resistance	$V_{GS} = 0.5V, f = 1M$	V _{GS} = 0.5V, f = 1MHz		2.2	-	Ω
$Q_{g(ToT)}$	Total Gate Charge	$V_{GS} = 0$ to 10V	V _{DD} = 64V	-	36	54	nC
$Q_{g(th)}$	Threshold Gate Charge	$V_{GS} = 0$ to 2V	$V_{GS} = 0 \text{ to } 2V$ $I_D = 80A$		4.6	-	nC
Q_{gs}	Gate-to-Source Gate Charge		_	-	13	-	nC
Q_{gd}	Gate-to-Drain "Miller" Charge			-	8.5	-	nC

Switching Characteristics

t_{on}	Turn-On Time		-	-	70	ns
t _{d(on)}	Turn-On Delay		-	13	-	ns
t _r	Rise Time	V _{DD} = 40V, I _D = 80A,	-	34	-	ns
t _{d(off)}	Turn-Off Delay	V_{GS} = 10V, R_{GEN} = 6Ω	-	22	-	ns
t _f	Fall Time		-	9	-	ns
t _{off}	Turn-Off Time		-	-	46	ns

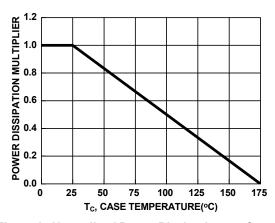
Drain-Source Diode Characteristics

V _{SD}	Source-to-Drain Dioge Voltage	I _{SD} =80A, V _{GS} = 0V	-	-	1.25	V
		I_{SD} = 40A, V_{GS} = 0V	-	-	1.2	٧
t _{rr}	Reverse-Recovery Time	I _F = 80A, dI _{SD} /dt = 100A/μs	-	49	64	ns
Q _{rr}	Reverse-Recovery Charge		-	40	53	nC

Note:

^{4:} The maximum value is specified by design at T_J = 175°C. Product is not tested to this condition in production.

Typical Characteristics



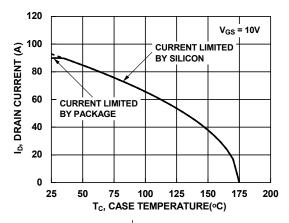
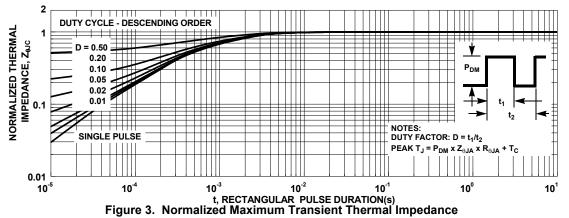


Figure 1. Normalized Power Dissipation vs. Case **Temperature**

Figure 2. Maximum Continuous Drain Current vs. **Case Temperature**



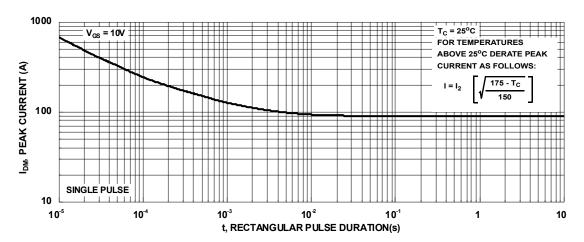


Figure 4. Peak Current Capability

Typical Characteristics

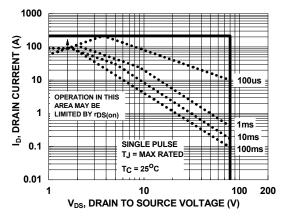
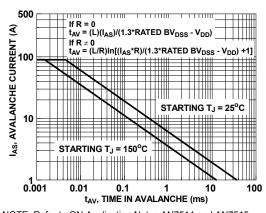


Figure 5. Forward Bias Safe Operating Area



NOTE: Refer to ON Application Notes AN7514 and AN7515

Figure 6. Unclamped Inductive Switching

Capability

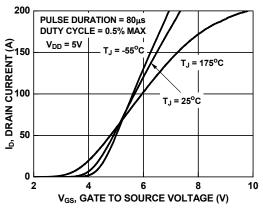


Figure 7. Transfer Characteristics

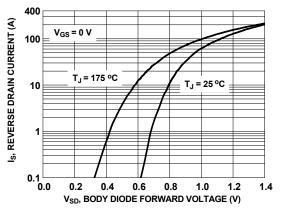


Figure 8. Forward Diode Characteristics

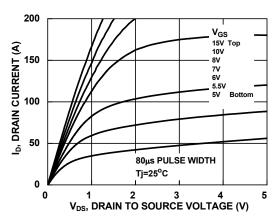


Figure 9. Saturation Characteristics

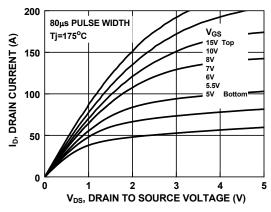


Figure 10. Saturation Characteristics

Typical Characteristics

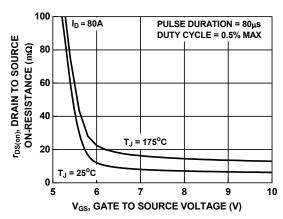


Figure 11. R_{DSON} vs. Gate Voltage

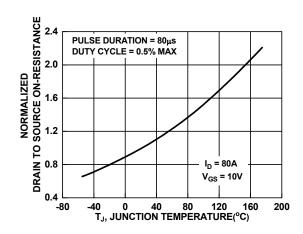


Figure 12. Normalized R_{DSON} vs. Junction Temperature

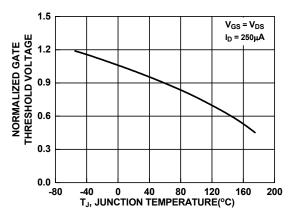


Figure 13. Normalized Gate Threshold Voltage vs. Temperature

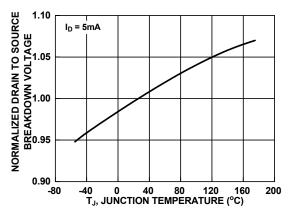


Figure 14. Normalized Drain to Source Breakdown Voltage vs. Junction Temperature

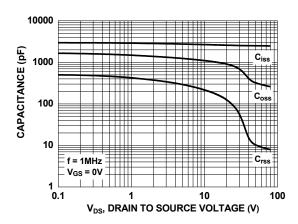


Figure 15. Capacitance vs. Drain to Source Voltage

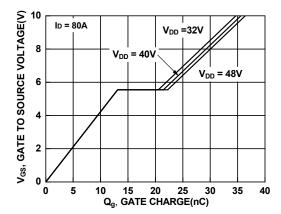
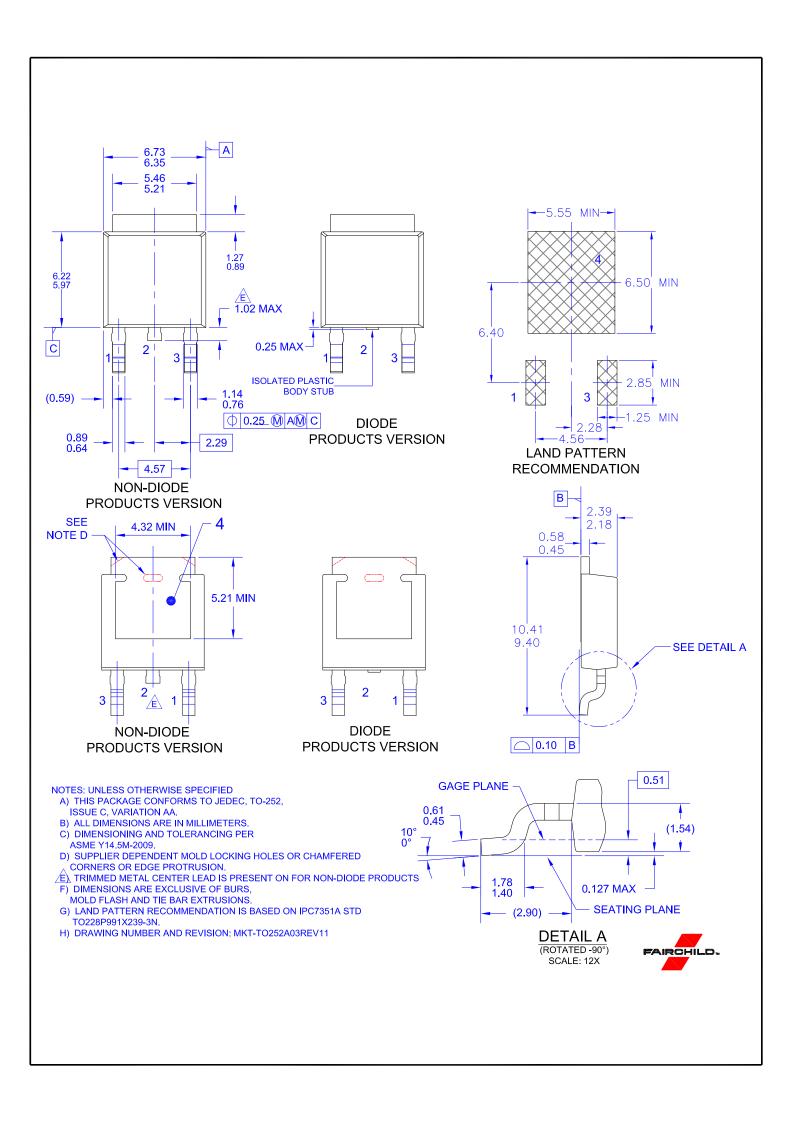


Figure 16. Gate Charge vs. Gate to Source Voltage



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